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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Stefan BADER et al.

Serial No.: 10/696,882

Filed: October 30, 2003

For: Method for Depositing a Material on a Substrate
WaferExaminer: Rao G. Nagesh
Group Art: 1722

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June 27, 2006
(Date of Deposit)

Thomas Langer

Name of applicant, assignee or Registered Representative

Signature
June 27, 2006
Date of Signature

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

SIR:

In response to the Office Action dated March 27, 2006, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.